**Description**

The SP1020 includes back-to-back Zener diodes fabricated in a proprietary silicon avalanche technology to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes above the maximum level specified in the IEC 61000-4-2 international standard (Level 4, ±8kV contact discharge) without performance degradation. The back-to-back configuration provides symmetrical ESD protection for data lines when AC signals are present.

**Features**

- RoHS compliant, Halogen-free and Lead-free
- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, IEC 61000-4-5, 2nd Edition, 5A (tₚ=8/20μs)
- Low capacitance of 20pF (@Vᵣ=0V)
- Low leakage current of 0.1μA at 5V
- Industry’s smallest ESD footprint available (01005)

**Applications**

- Mobile Phones
- Smart Phones
- Portable Medical
- Digital Cameras
- Wearable Technology
- Portable Navigation Devices
- Tablets

**Life Support Note:**

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.
TVS Diode Arrays (SPA® Diodes)
General Purpose ESD Protection - SP1020 Series

Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Value</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>I_{PP}</td>
<td>Peak Current (t_p=8/20μs)</td>
<td>5.0</td>
<td>A</td>
</tr>
<tr>
<td>T_{OP}</td>
<td>Operating Temperature</td>
<td>-40 to 125</td>
<td>°C</td>
</tr>
<tr>
<td>T_{STOR}</td>
<td>Storage Temperature</td>
<td>-55 to 150</td>
<td>°C</td>
</tr>
</tbody>
</table>

Notes:
1. CAUTION: Stresses above those listed in “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Rating</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Storage Temperature Range</td>
<td>-55 to 150</td>
<td>°C</td>
</tr>
<tr>
<td>Maximum Junction Temperature</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Maximum Lead Temperature (Soldering 20-40s)</td>
<td>260</td>
<td>°C</td>
</tr>
</tbody>
</table>

Electrical Characteristics (T_{OP}=25°C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse Standoff Voltage</td>
<td>V_{RWM}</td>
<td>V_r=3.3V with 1 pin at GND^1</td>
<td>6.0</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>V_r=5V with 1 pin at GND</td>
<td>10</td>
<td>nA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Leakage Current</td>
<td>I_{LEAK}</td>
<td>V_r=1A, t_p=8/20μs, Fwd</td>
<td>0.1</td>
<td>nA</td>
<td>0.5</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I_{LEAK}=2A, t_p=8/20μs, Fwd</td>
<td>9.3</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Clamp Voltage^1</td>
<td>V_C</td>
<td>I_{PP}=1A, t_p=8/20μs, Fwd</td>
<td>10.0</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Dynamic Resistance^2</td>
<td>R_{DYN}</td>
<td>TLP, t_p=100ns, I/O to GND, 8/20μs</td>
<td>0.32</td>
<td>Ω</td>
<td></td>
<td></td>
</tr>
<tr>
<td>ESD Withstand Voltage^1</td>
<td>V_{ESD}</td>
<td>IEC 61000-4-2 (Contact Discharge)</td>
<td>±30</td>
<td>kV</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Diode Capacitance^1</td>
<td>C_d</td>
<td>Reverse Bias=0V</td>
<td>20</td>
<td>pF</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Note:
1 Parameter is guaranteed by design and/or device characterization.
2 Transmission Line Pulse (TLP) with 100ns width and 200ps rise time.

Pulse Waveform

Capacitance vs. Reverse Bias
**Soldering Parameters**

**Reflow Condition**
- Pb – Free assembly

**Pre Heat**
- Temperature Min \( T_{\text{S(min)}} \) 150°C
- Temperature Max \( T_{\text{S(max)}} \) 200°C
- Time (min to max) \( t_{\text{S}} \) 60 – 180 secs

Average ramp up rate (Liquidus) Temp \( T_{L} \) to peak
- \( T_{L} \) to \( T_{P} \) - Ramp-up Rate 3°C/second max

**Reflow**
- Temperature \( T_{L} \) (Liquidus) 217°C
- Temperature \( t_{L} \) 60 – 150 seconds

**Peak Temperature (\( T_{P} \))** 260\(^\circ\)C

Time within 5°C of actual peak Temperature \( t_{p} \) 20 – 40 seconds

Ramp-down Rate 6°C/second max

Time 25°C to peak Temperature \( T_{P} \) 8 minutes Max.

Do not exceed 260°C

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**Part Marking System**

- SP 1020 - 01
- W T G

- TVS Diode Arrays (SPA® Diodes)
- Series
- Number of Channels
- Package
- W: 01005 Flipchip

**Ordering Information**

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package</th>
<th>Marking</th>
<th>Min. Order Qty.</th>
</tr>
</thead>
<tbody>
<tr>
<td>SP1020-01WTG</td>
<td>01005 Flipchip</td>
<td>• •</td>
<td>15000</td>
</tr>
</tbody>
</table>

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Specifications are subject to change without notice.
Revision: 11/23/16
### Package Dimensions — 01005 Flipchip

#### TOP VIEW

- **A**: 0.153 to 0.181
- **A1**: 0.008 to 0.0143
- **A2**: 0.145 to 0.195
- **D**: 0.205 to 0.255
- **E**: 0.415 to 0.465

#### BOTTOM VIEW

- **E**: 0.085
- **F**: 3.50
- **P1**: 2.00
- **W**: 8.00

#### Symbol

- **A**: 0.008 to 0.020
- **A1**: 0.008 to 0.014
- **A2**: 0.008 to 0.014
- **D**: 0.008 to 0.014
- **E**: 0.008 to 0.014

#### Stencil opening

- **W**: 0.16
- **P2**: 0.24

#### Recommended Solder Pad Footprint and Stencil opening

- Thickness of Stencil opening is 0.08mm

### Embossed Carrier Tape & Reel Specification — 01005 Flipchip

- **A0**: 0.30
- **B0**: 0.51
- **K0**: 0.20
- **F**: 3.50
- **P1**: 2.00
- **W**: 8.00

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SP1020 Series